

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT7577655

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HYEONGSOON PARK	08/30/2022
JEONGGYU JO	08/30/2022
HYUNWOO SIM	08/30/2022
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAMSUNG ELECTRONICS CO., LTD.
<b>Street Address:</b>	129, SAMSUNG-RO, YEONGTONG-GU
<b>City:</b>	SUWON-SI, GYEONGGI-DO
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	16677
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17961111
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	202-293-0804
<b>Email:</b>	usdocketing@jeffersonip.com
<b>Correspondent Name:</b>	JEFFERSON IP LAW, LLP
<b>Address Line 1:</b>	1130 CONNECTICUT AVE., NW SUITE 420
<b>Address Line 4:</b>	WASHINGTON, D.C. 20036
<b>ATTORNEY DOCKET NUMBER:</b>	0203-3186
<b>NAME OF SUBMITTER:</b>	MAENG-HO SHIN
<b>SIGNATURE:</b>	/Maeng-Ho SHIN/
<b>DATE SIGNED:</b>	10/06/2022
<b>Total Attachments: 4</b>	
source=0203-3186AssignmentAsFiled#page1.tif	
source=0203-3186AssignmentAsFiled#page2.tif	
source=0203-3186AssignmentAsFiled#page3.tif	
source=0203-3186AssignmentAsFiled#page4.tif	

# RECORDATION FORM COVER SHEET PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)**

1) Hyeonsoon PARK, 2) Jeonggyu JO, and 3) Hyunwoo SIM

Additional name(s) of conveying party(ies) attached?  Yes  No

**2. Name and address of receiving party(ies)**

Name: Samsung Electronics Co., Ltd.

Internal Address: \_\_\_\_\_

Street Address: 129, Samsung-ro, Yeongtong-gu

City: Suwon-si, Gyeonggi-do

State: \_\_\_\_\_

Country: Republic of Korea Zip: 16677

Additional name(s) & address(es) attached?  Yes  No

**3. Nature of conveyance/Execution Date(s):**

Execution Date(s) August 30, 2022

- Assignment  Merger
- Security Agreement  Change of Name
- Joint Research Agreement
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other \_\_\_\_\_

**4. Application or patent number(s):**

A. Patent Application No.(s)  
17/961,111

This document is being filed together with a new application.

B. Patent No.(s)

Additional numbers attached?  Yes  No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Jefferson IP Law, LLP

Internal Address: Gregory L. Clinton

Street Address: 1130 Connecticut Ave., NW, Suite 420

City: Washington

State: District of Columbia Zip: 20036

Phone Number: 202-293-0804

Fax Number: 202-403-3587

Email Address: usdocketing@jeffersonip.com

**6. Total number of applications and patents involved:** One

- 7. Total fee (37 CFR 1.21(h) & 3.41) \$** \_\_\_\_\_
- Authorized to be charged by credit card
  - Authorized to be charged to deposit account
  - Enclosed
  - None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_

b. Deposit Account Number \_\_\_\_\_  
Authorized User Name \_\_\_\_\_

**9. Signature:**

\_\_\_\_\_/Gregory L. CLINTON/ Reg. #59,134  
Signature

\_\_\_\_\_  
Date

\_\_\_\_\_  
Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 4

Documents to be recorded (including cover sheet) should be faxed to (571) 273-0140, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

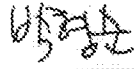
**PATENT**  
**REEL: 061336 FRAME: 0265**





DOCKET NO.: 0203-3186  
CLIENT REF.: YPF202011-0061/US-PCT  
SAMSUNG REF.: GM-201912-024-1-US0

Signature of Inventor:



Hyeongsoon PARK

2022.8.30

Date

Signature of Inventor:

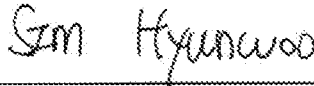


Jeonggyu JO

2022.8.30

Date

Signature of Inventor:



Hyunwoo SIM

2022.8.30

Date